Product name	**HP RP5800 computer (DVD-PC-4)**
Identification code(s)	DVD-PC-4 HP RP5800: 45980017108x
Total weight [kg]	10kg
Manufacturer	**Hewlett Packard Nederland B.V.**
Address	Startbaan 16
Zip code	1187XR Amstelveen
Country	The Netherlands
Electronic info	DMR155308-579O-WEEE-COMPUTER_HP_RP5800_v00.pdf

Information in this document is incorporated from the HP document (HP—EL-MF877-01) located on http://www.hp.com/hpinfo/globalcitizenship/environment/productdata/disassemblydesktop-pc.html

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Product End-of-Life Disassembly Instructions

Product Category: Personal Computers
Marketing Name / Model [List multiple models if applicable.]
HP rp5800 Point of Sale System
Name / Model #2
Name / Model #3
Name / Model #4
Name / Model #5

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	4
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		3
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		

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Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screwdriver	T-15
Micro shear	170II
Screwdriver	PH1
SW5 x 125	5.0
Description #5	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the access panel.(see Figure 1 below)
2. Remove fan duct and clapboard from chassis.(see Figure 2-6 below)
3. Remove front PSU fan from ODD cage.(see Figure 7-8 below)
4. Remove PSU from chassis.(see Figure 9-10 below)
5. Remove the Riser card from the MB(see Figure 11-15 below)
6. Remove SATA cable and HDD from chassis (see Figure 16-22 below)
7. Remove front bezel from chassis.(see Figure 23 below)
8. Remove front system fan from chassis.(see Figure 24-26 below)
9. Remove FIO and speaker from chassis.(see Figure 27-29 below)
10. Remove the Memory from the board.(see Figure 30 below)
11. Remove the CPU from the board .(see Figure 31-33 below)
12. Remove the battery from the system board.(see Figure 34 below)
13. Remove the COMB card from the MB.(see Figure 35 below)
14. Remove M/B from chassis.(see Figure 36-37 below)
15. Remove PSU cover.(see Figure 38-39 below)
16. Disconnect all the cables and remove the Electrolytic Capacitors.(see Figure 40-50 below)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Figure 1 Remove the access panel



Figure 2 Rotate the HDD cage up

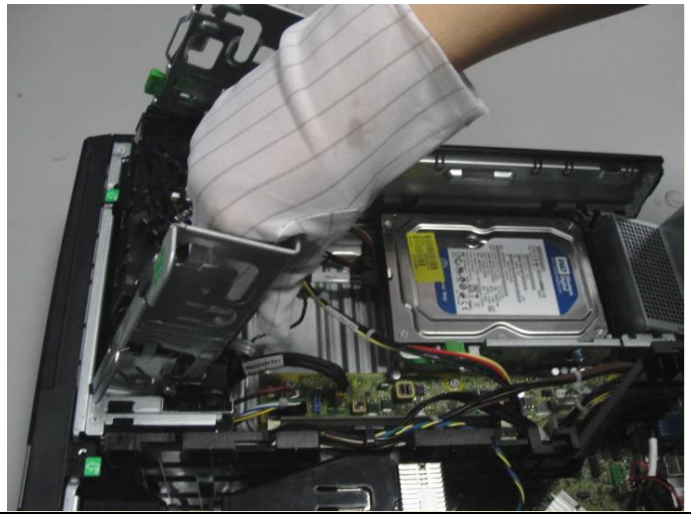


Figure 3 Disconnect the cables from fan duct

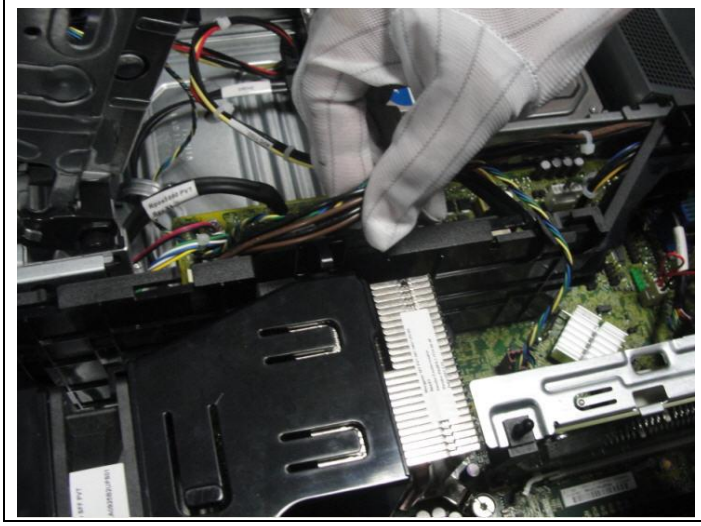


Figure 4 Remove fan duct from the board



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Figure 5 Loose the clapboard from chassis

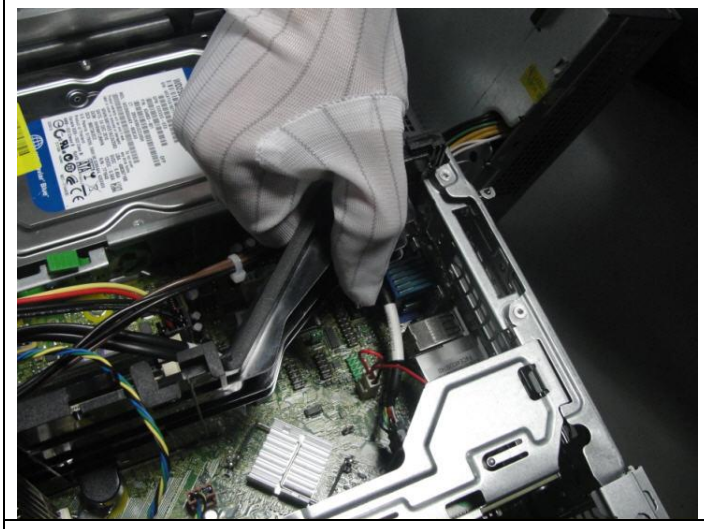


Figure 6 Remove the clapboard from chassis

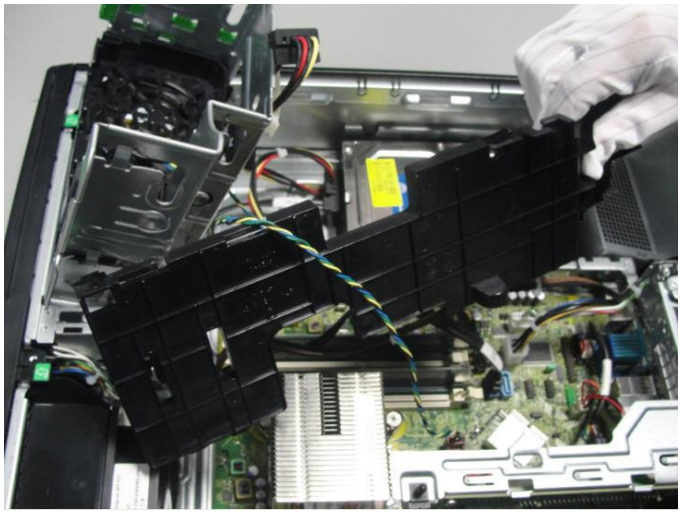


Figure 7 Disconnect front PSU fan cable from MB



Figure 8 Remove front PSU fan from ODD cage

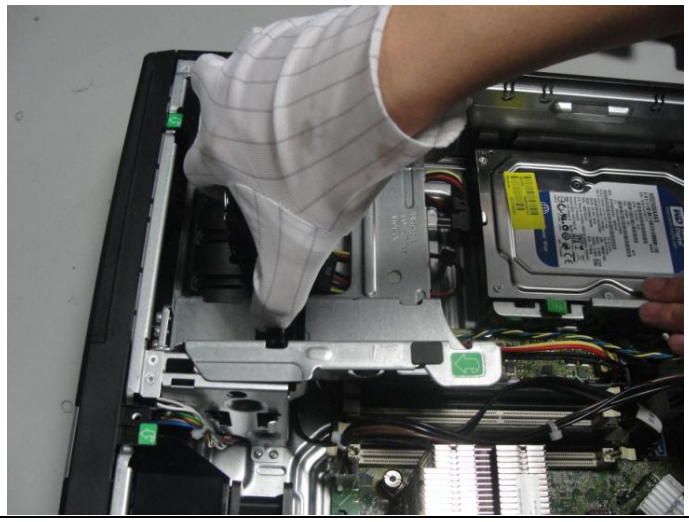


Figure 9 Disconnect MB main power and PSU fan cable from MB

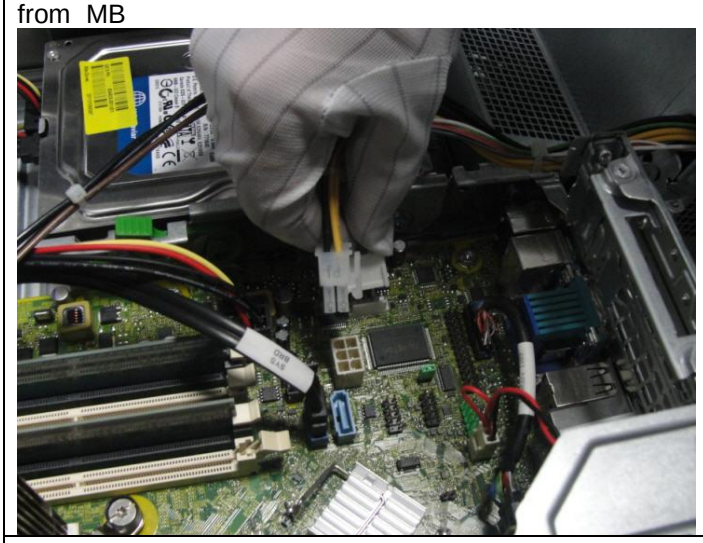


Figure 10 Remove CPU power cable from MB

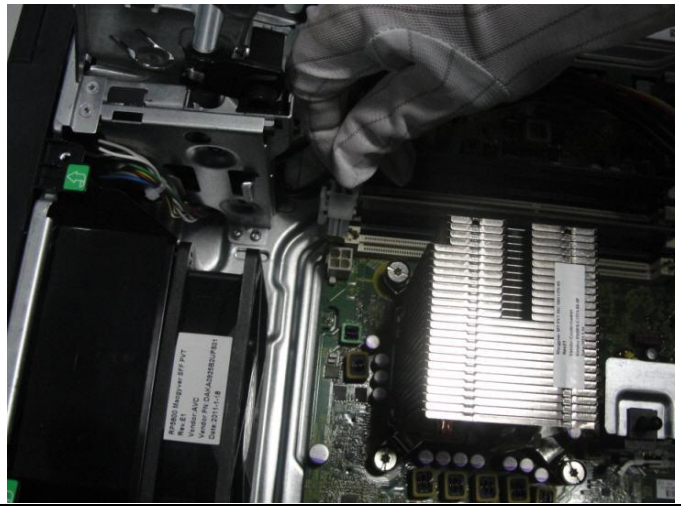


Figure 11 Remove PSU from MB



Figure 12 Loose PCI latch cover from chassis



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Figure 13 Remove two FH vent PCI slot from chassis

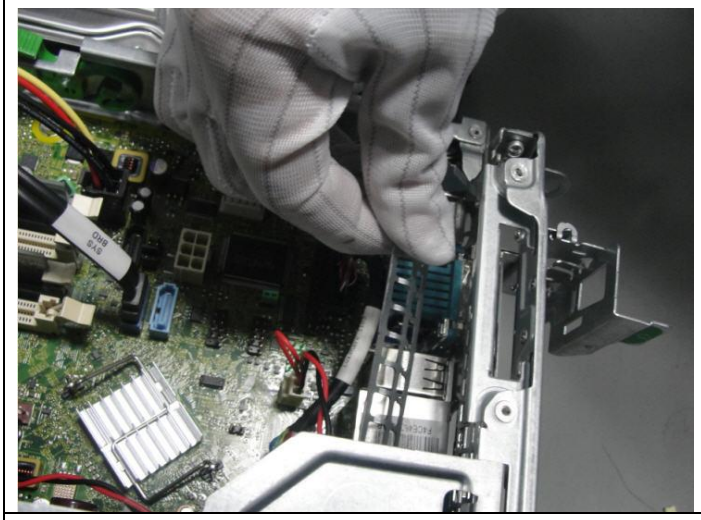


Figure 14 Disconnect hood sensor from MB

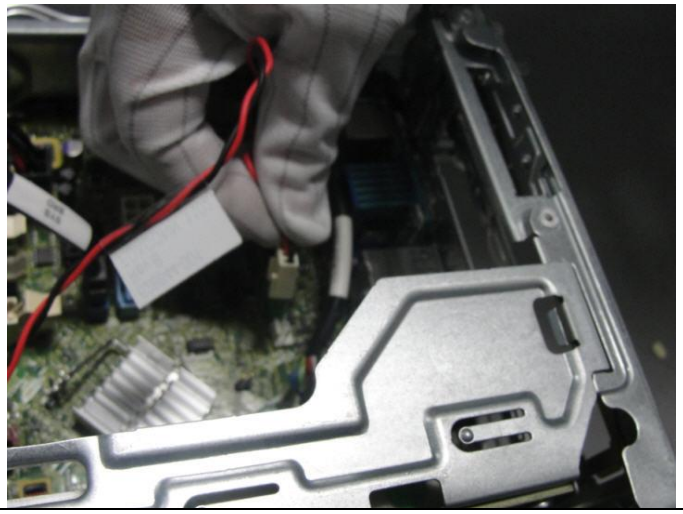


Figure 15 Remove the riser card form MB and chassis

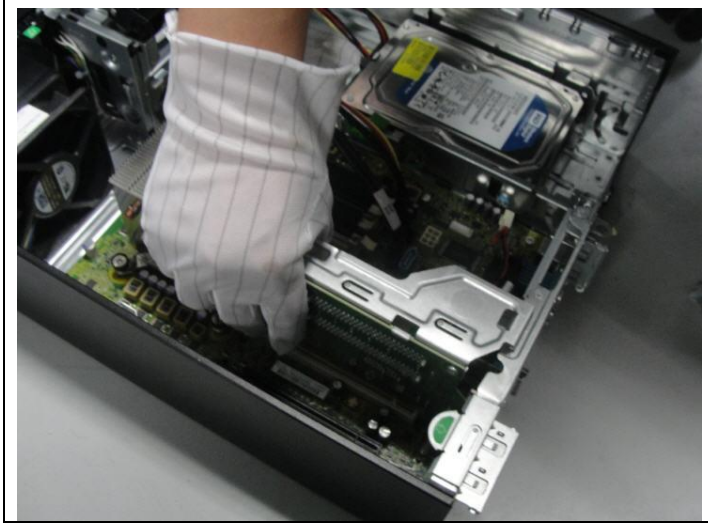


Figure 16 Disconnect SATA power cable from MB

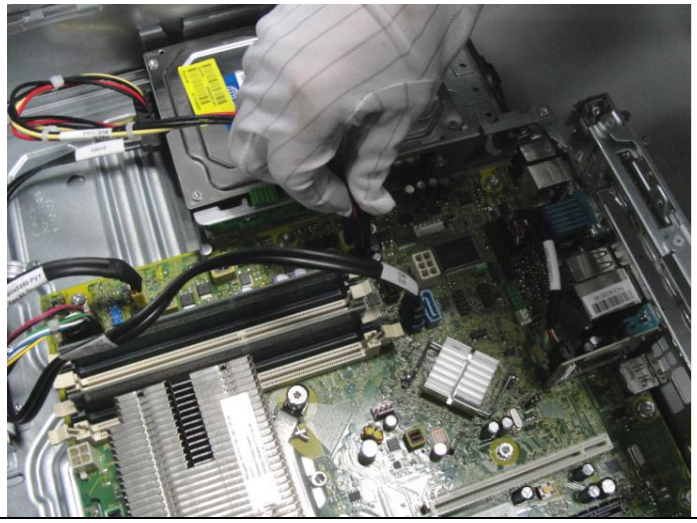


Figure 17 Remove SATA power cable from HDD

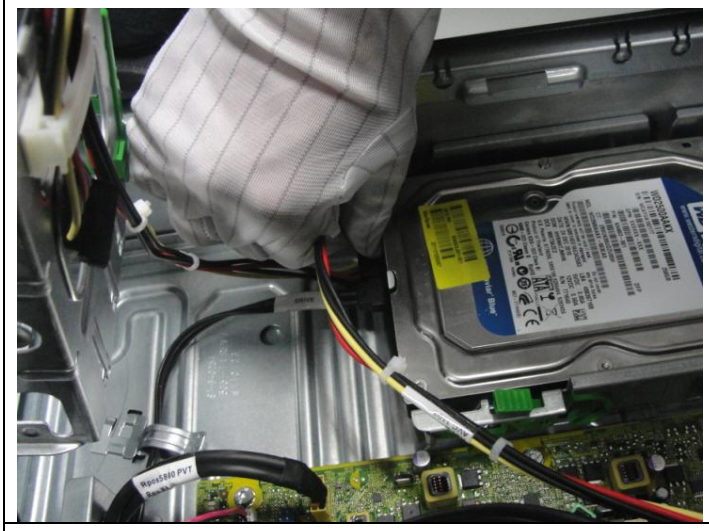


Figure 18 Loose the cable tie and ODD cage and remove SATA power cable from chassis

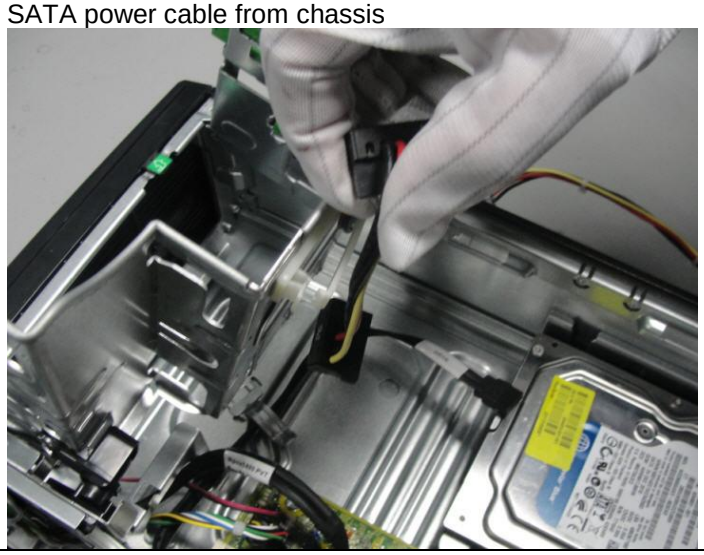


Figure 19 Remove SATA data cable from MB

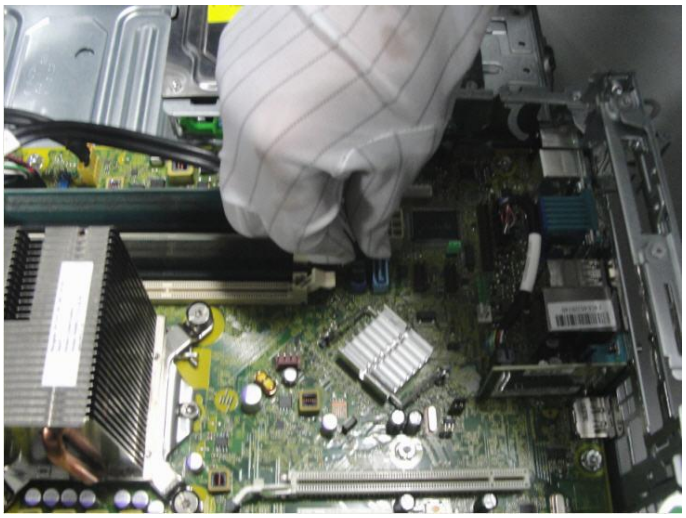


Figure 20 Remove SATA data cable from HDD



Figure 21 Press the HDD's latch on HDD cage.



Figure 22 Remove the HDD from cage



Figure 23 Remove front panel



Figure 24 Disconnect front system fan cable from MB

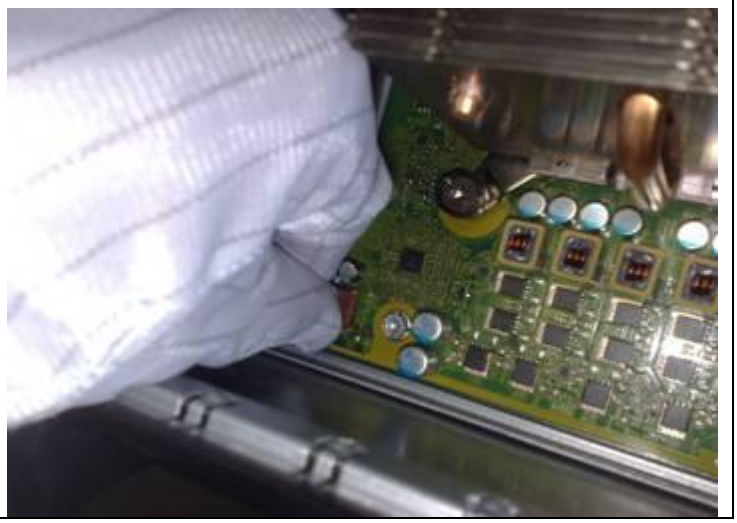


Figure 25 Loose the front system fan holder hook from chassis



Figure 26 Remove front system fan holder



Figure 27 Disconnect FIO cables from MB



Figure 28 Loose screw of FIO and remove FIO



Figure 29 Loose screws of speaker and remove speaker



Figure 30 Remove the Memory from MB



Figure 31 Loose the screws and remove heat sink



Figure 32 Rotate CPU socket handle and open it up



Figure 33 Remove the CPU from MB



Figure 34 Remove the battery from MB



Figure 35 Loose the screws of COMB card and remove



Figure 36 Loose MB screws from chassis



Figure 37 Remove M/B from chassis



Figure 38 Remove the screws on the PSU chassis

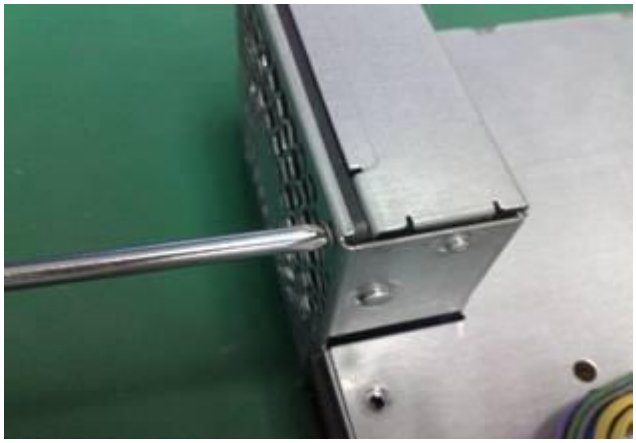


Figure 39 Lift the cover off the power supply

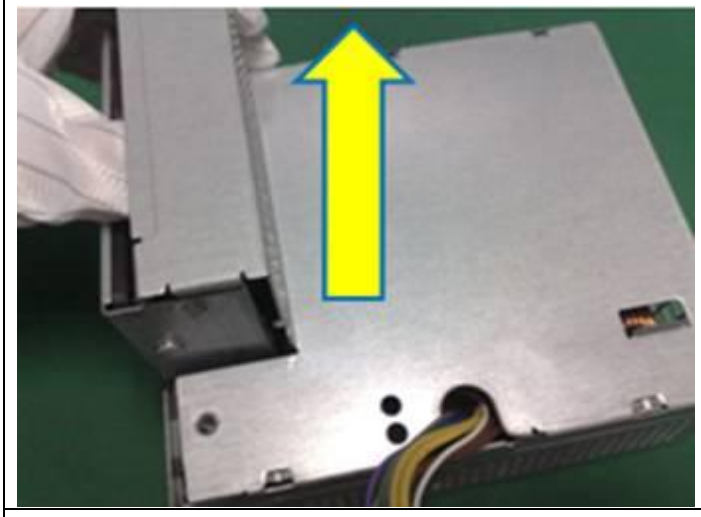


Figure 40 Remove the four screws on the board



Figure 41 Using Soldering Iron, heat the solder of the cables which connect to the PCA, then remove them

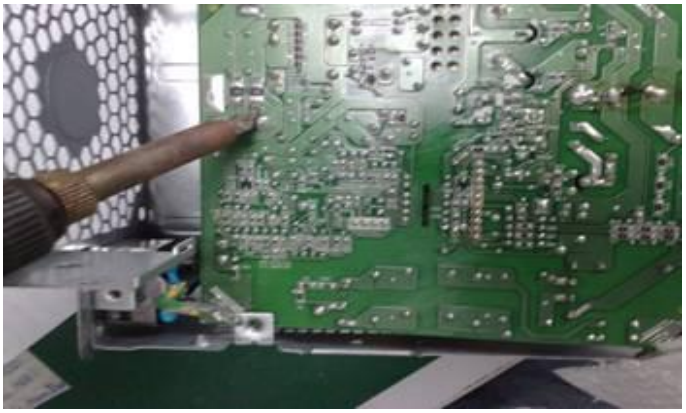


Figure 42 Remove the power supply cable from the power supply



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Figure 43 Heat the solder of Electrolytic Capacitors



Figure 44 Remove the Electrolytic Capacitors



Figure 45 Heat the solder of Electrolytic Capacitors greater than 2.5cm in diameter or height

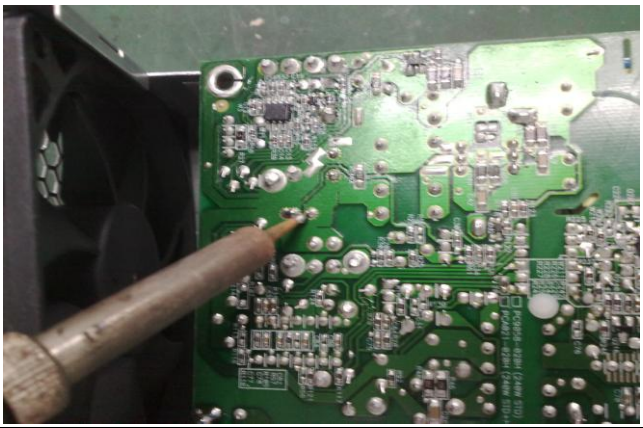


Figure 46 Remove the Electrolytic Capacitors（For Acbel 240W EPA）

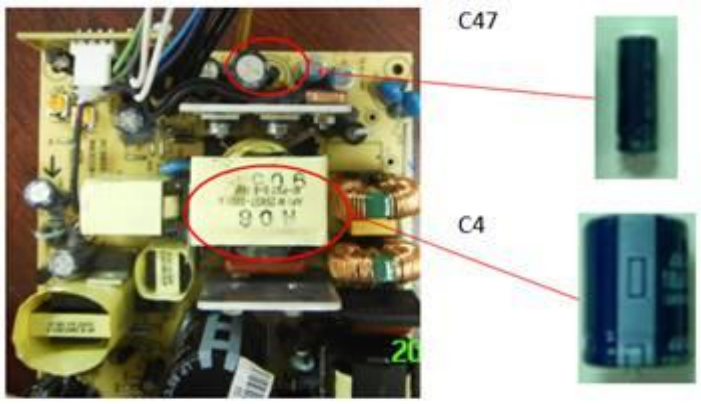


Figure 47 Remove the Electrolytic Capacitors（For Liteon EPA PSU）



Figure 48 Remove the Electrolytic Capacitors（For Delta EPA PSU）

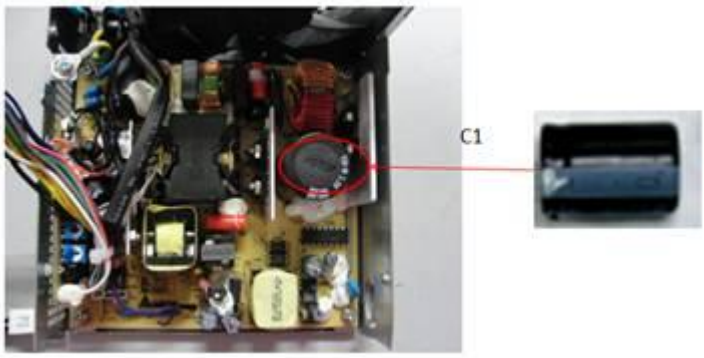


Figure 49 Remove the Electrolytic Capacitors（For Chicony EPA PSU）	Figure 50 Remove the Electrolytic Capacitors（For Bestec EPA PSU）
